

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# **SPECIFICATION**

(Reference sheet)

· Supplier : Samsung electro-mechanics · Samsung P/N : CL10C120JB8NNNC

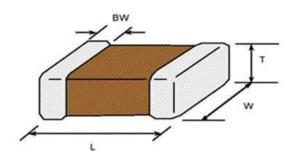
· Product : Multi-layer Ceramic Capacitor · Description : CAP, 12pF, 50V, ± 5%, C0G, 0603

### A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>120</u> <u>J</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ® ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor			
② Size	0603 (inch code)	L: 1.60 ± 0.10 mm	W: 0.80 ± 0.10 mm	
3 Dielectric	C0G	8 Inner electrode	Ni	
Capacitance	<b>12</b> pF	Termination	Cu	
⑤ Capacitance	± 5 %	Plating	Sn 100% (Pb Free)	
tolerance		9 Product	Normal	
Rated Voltage	50 V	Special	Reserved for future use	
7 Thickness	0.80 ± 0.10 mm	① Packaging	Cardboard Type, 7" reel	

#### B. Structure and dimension



Samsung P/N	Dimension(mm)			
(Lead Free)	L	W	Т	BW
CL10C120JB8NNNC	1.60 ± 0.10	0.80 ± 0.10	0.80 ± 0.10	0.30 ± 0.20

#### C. Samsung Reliability Test and Judgement condition

Capacitance       Within specified tolerance         Q       640 min         Insulation       10,000Mohm or 500Mohm×μF         Resistance       Whichever is smaller         Appearance       No observed exterior appearance	1Mt±10% 0.5~5Vrms  Rated Voltage 60~120 sec.  Microscope (´10)  300% of the rated voltage			
Insulation       10,000Mohm or 500Mohm×μF         Resistance       Whichever is smaller	Microscope ('10)			
Resistance Whichever is smaller	Microscope ('10)			
Annearance No obnormal exterior annearance				
Appearance No abnormal exterior appearance	300% of the rated voltage			
Withstanding No dielectric breakdown or	300% of the rated voltage			
Voltage mechanical breakdown				
Temperature C0G	COG			
Characteristics (From -55 °C to 125 °C, Capacitano	(From -55 ℃ to 125 ℃, Capacitance change should be within ±30PPM/ ℃)			
Adhesive Strength No peeling shall be occur on the	500g×F, for 10±1 sec.			
of Termination terminal electrode				
Bending Strength Capacitance change :	Bending to the limit (1mm)			
within ±5% or ±0.5pF whichever is	larger with 1.0mm/sec.			
Solderability More than 75% of terminal surface	e SnAg3.0Cu0.5 solder			
is to be soldered newly	245±5℃, 3±0.3sec.			
	(preheating : 80~120 ℃ for 10~30sec.)			
Resistance to Capacitance change :	Solder pot : 270±5℃, 10±1sec.			
Soldering heat within ±2.5% or ±0.25pF whicheve	r is larger			
Tan δ, IR : initial spec.				
Vibration Test Capacitance change :	Amplitude : 1.5mm			
within ±2.5% or ±0.25pF whicheve	r is larger From 10Hz to 55Hz (return : 1min.)			
Tan δ, IR : initial spec.	2hours ´ 3 direction (x, y, z)			
Moisture Capacitance change :	With rated voltage			
<b>Resistance</b> within ±7.5% or ±0.75pF whicheve	r is larger 40±2℃, 90~95%RH, 500+12/-0hrs			
Q: 140 min				
IR: 500Mohm or 25Mohm	× μF			
Whichever is smaller				
High Temperature Capacitance change :	With 200% of the rated voltage			
Resistance within ±3% or ±0.3pF whichever is	larger Max. operating temperature			
Q: 305 min	1000+48/-0hrs			
IR: 1,000Mohm or 50Mohr	n × μF			
Whichever is smaller				
Temperature Capacitance change :	1 cycle condition			
Cycling within ±2.5% or ±0.25pF whicheve	r is larger Min. operating temperature → 25℃			
Tan δ, IR : initial spec.	$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}$ C			
	5 cycle test			

<sup>\*</sup> The reliability test condition can be replaced by the corresponding accelerated test condition.

### D. Recommended Soldering method:

Reflow (Reflow Peak Temperature: 260+0/-5°C, 10sec. Max)



△ Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

## - Disclaimer & Limitation of Use and Application -

The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

Please note that any misuse of the products deviating from products specifications or information provided in this Spec sheet may cause serious property damages or personal injury.

We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.

If you have any questions regarding this 'Limitation of Use and Application', you should first contact our sales personnel or application engineers.

- ① Aerospace/Aviation equipment
- ② Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- Military equipment
- 5 Disaster prevention/crime prevention equipment
- 6 Any other applications with the same as or similar complexity or reliability to the applications set forth above.